

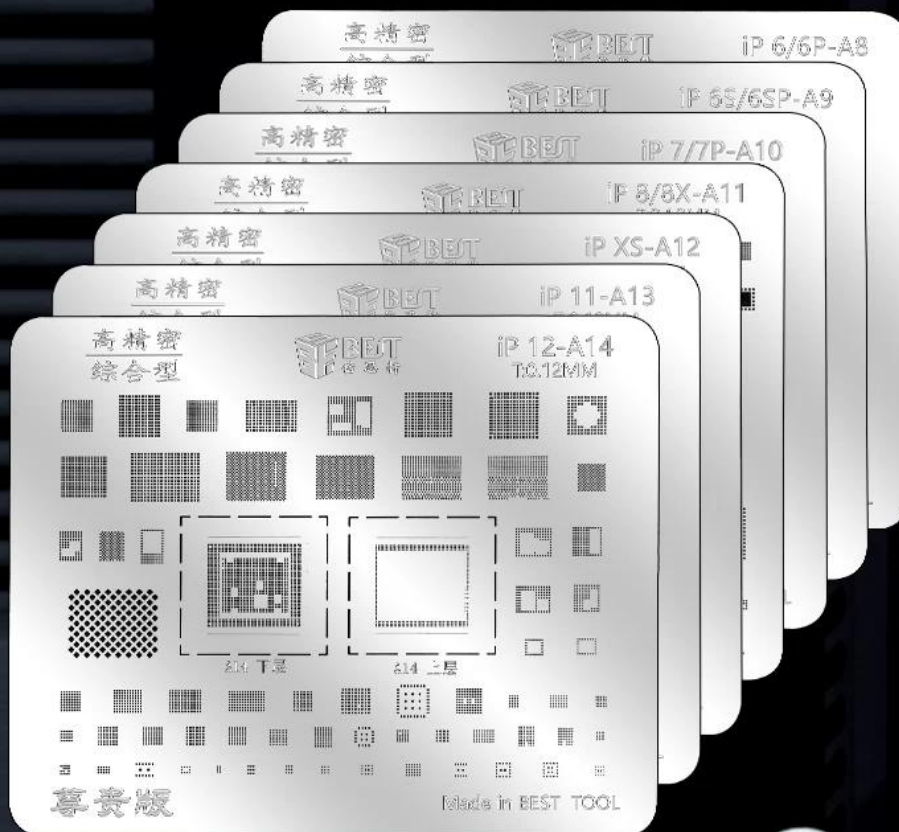


# BGA IC

## SOLDERING REBALLING STENCIL

High toughness

Strong magnetic steel



# Product Usage



Model NO.	BST-iP (A8-A14)	Melting point	700℃
Name	Reballing Stencil	G.W.	25.8g
Material	Strong magnetic steel	Size	141*103*13.1mm





# Four characteristics



Semi-etching process



Cooling hole design



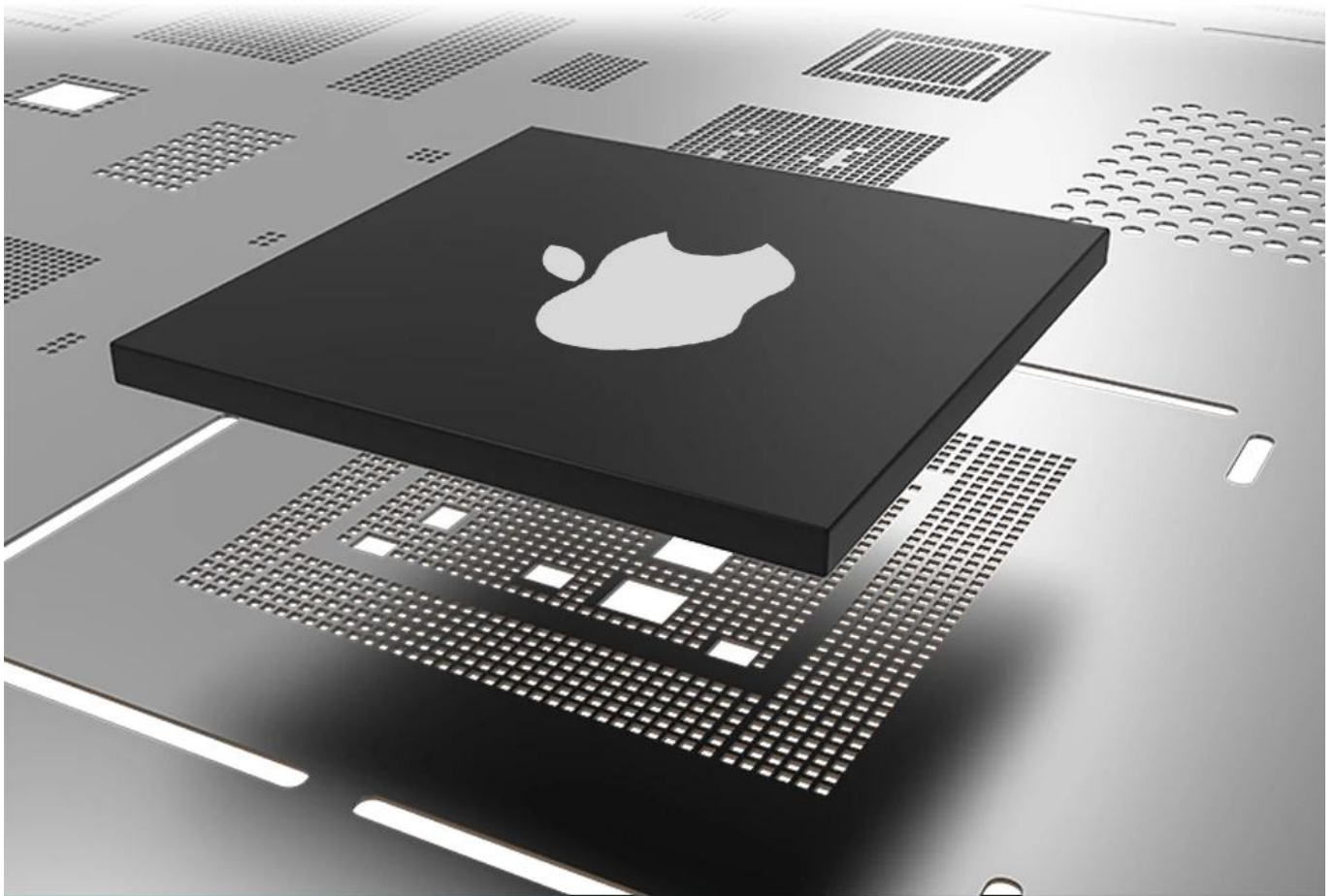
Square hole



Precise alignment

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Easily mounted on the steel mesh to make the chip fit  
more closely with the mesh Therefore.



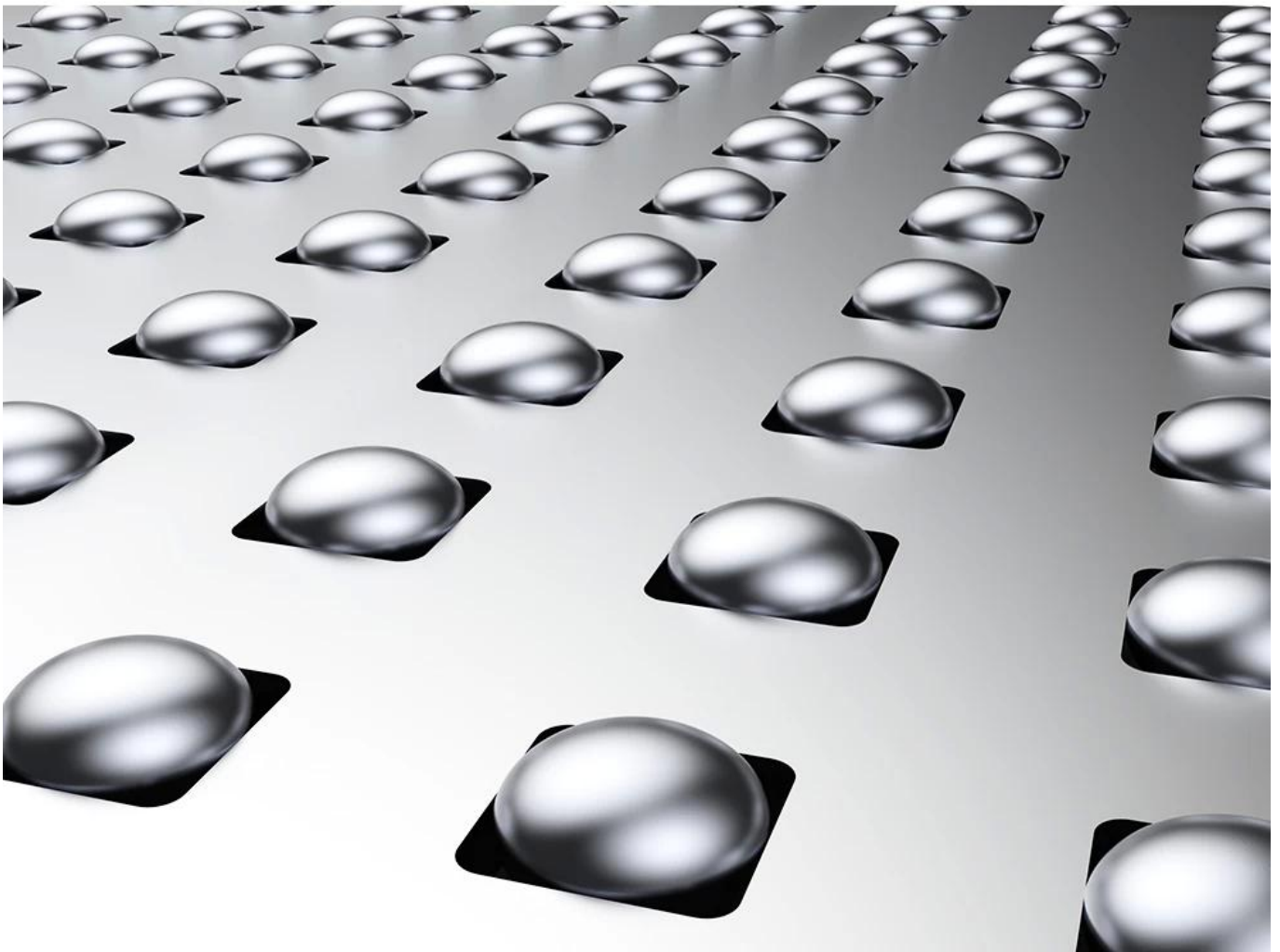
Hard and wear resistant  
vertical hole position, no burr





## Precision Reballing Stencil

Tin point is neat and tidy



G.W.:25.8G

